

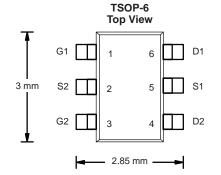
Dual N-Channel 20 V (D-S) MOSFET

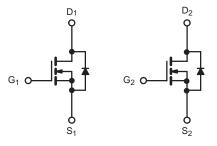
PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)			
20	0.022 at V_{GS} = 4.5 V	6.0	1.8 nC			
	0.028 at V _{GS} = 2.5 V	5.0	1.0 110			

FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- TrenchFET[®] Power MOSFET
- 100 % Rg Tested
- Compliant to RoHS Directive 2002/95/EC







N-Channel MOSFET

N-Channel MOSFET

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	20	V	
Gate-Source Voltage		V _{GS}	± 12	v	
	T _C = 25 °C		6.0		
Continuous Drain Current ($T_1 = 150 \ ^{\circ}C$)	T _C = 70 °C	I _D	4.0		
	T _A = 25 °C	טי	3.5 ^{b, c}		
	T _A = 70 °C		2.8 ^{b, c}	A	
Pulsed Drain Current		I _{DM}	18		
	T _C = 25 °C		1.17		
Continuous Source-Drain Diode Current	T _A = 25 °C	۱ _S	0.95 ^{b, c}		
	T _C = 25 °C		1.6		
Maximum Power Dissipation	T _C = 70 °C	PD	1.0	w	
	T _A = 25 °C	טי	1.14 ^{b, c}	~~~~	
	T _A = 70 °C		0.73 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		
Soldering Recommendations (Peak Tempera	ature) ^{d, e}		260		

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{b, d}	t ≤ 5 s	R _{thJA}	93	110	°C/W
Maximum Junction-to-Foot	Steady State	R _{thJF}	75	90	0/00

Notes:

a. $T_C = 25 \ ^{\circ}C.$

b. Surface Mounted on 1" x 1" FR4 board.

c. t = 5 s.

d. Maximum under steady state conditions is 150 °C/W.

SPECIFICATIONS $T_J = 25 \degree C$,				-		
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	N			1	[
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_{D} = 250 \mu A$	20			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		29		mV/°C
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			- 4		<u> </u>
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	0.4		1.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0$ V, $V_{GS} = \pm 20$ V			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 20$ V, $V_{GS} = 0$ V			1	μA
	.033	V_{DS} = 20 V, V_{GS} = 0 V, T_{J} = 55 °C			10	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	10			Α
Drain Source On State Desistance	Rea()	$V_{GS} = 4.5 \text{ V}, I_D = 3.4 \text{ A}$		0.022		Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 2.5 \text{ V}, \text{ I}_{D} = 3.0 \text{ A}$		0.028		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 10 V, I _D = 3.4 A		10		S
Dynamic ^b					•	
Input Capacitance	C _{iss}			400		
Output Capacitance	C _{oss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		55		pF
Reverse Transfer Capacitance	C _{rss}			26		
	Qg	$V_{DS} = 10 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 3.4 \text{ A}$		3.7	6	nC
Total Gate Charge		V _{DS} = 10 V, V _{GS} = 4.5 V, I _D = 3.4 A		1.8	3	
Gate-Source Charge	Q _{gs}			0.74		
Gate-Drain Charge	Q _{gd}			0.42		
Gate Resistance	Rg	f = 1 MHz	1	5	10	Ω
Turn-On Delay Time	t _{d(on)}			10	20	-
Rise Time	t _r	$V_{DD} = 10 \text{ V}, \text{ R}_{L} = 5.6 \Omega$		15	30	
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}{\cong}2.7$ A, V_GEN = 4.5 V, R_g = 1 Ω		10	20	
Fall Time	t _f			10	20	
Turn-On Delay Time	t _{d(on)}			5	10	ns
Rise Time	t _r	$V_{DD} = 10 \text{ V}, \text{R}_{1} = 5.6 \Omega$		15	30	-
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 2.7 \text{ A}, V_{GEN} = 10 \text{ V}, \text{ R}_g = 1 \Omega$		10	20	
Fall Time	t _f	-		10	20	
Drain-Source Body Diode Characteristic	s					L
Continuous Source-Drain Diode Current	ا _S	T _C = 25 °C		1.2		
Pulse Diode Forward Current	I _{SM}			18		A
Body Diode Voltage	V _{SD}	$I_{S} = 2.7 \text{ A}, V_{GS} = 0 \text{ V}$		0.85	1.2	V
Body Diode Reverse Recovery Time	t _{rr}			10	20	ns
Body Diode Reverse Recovery Charge	Q _{rr}			4	10	nC
Reverse Recovery Fall Time	t _a	$I_F = 2.7 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, \text{ T}_J = 25 \text{ °C}$		6		
Reverse Recovery Rise Time	t _b			4		ns

Notes:

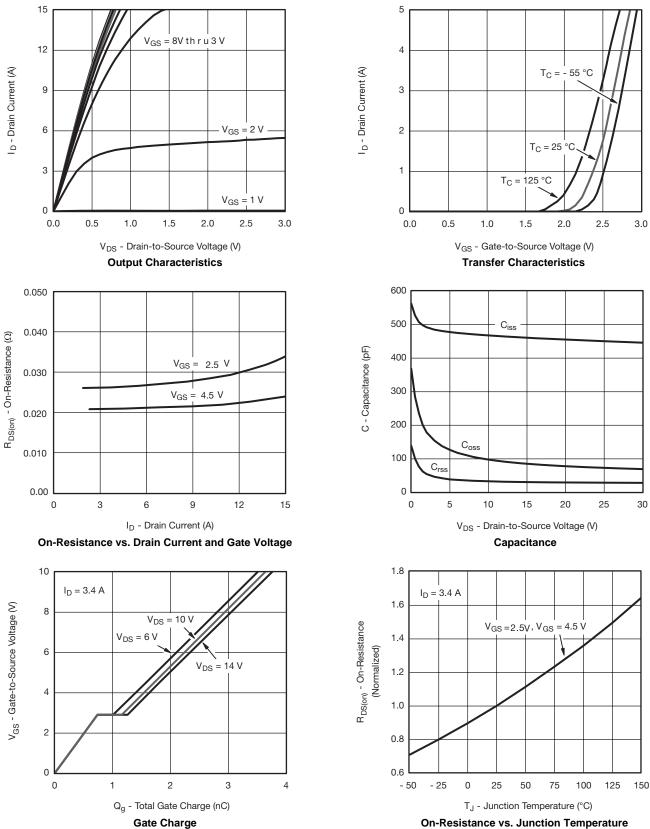
a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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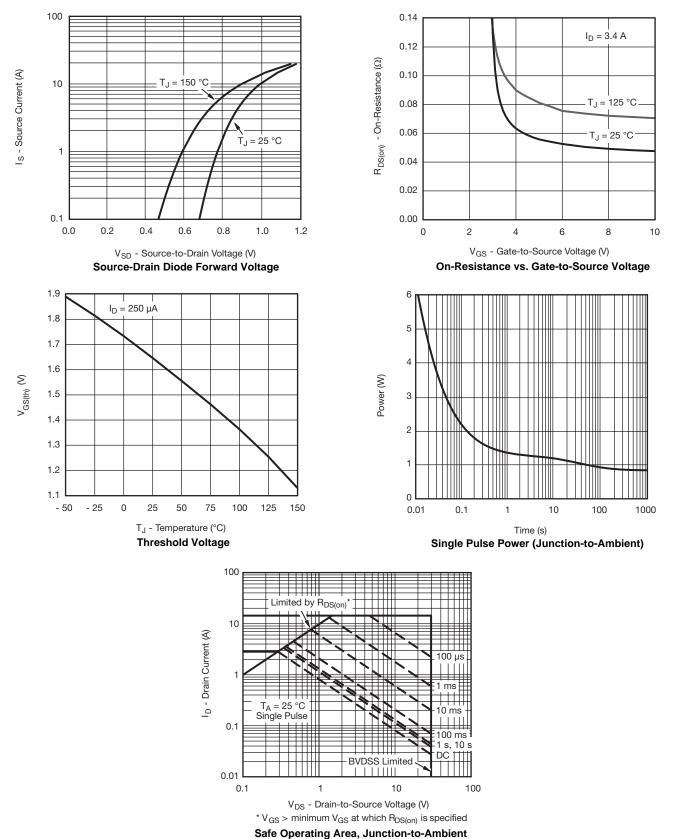
On-Resistance vs. Junction Temperature

30

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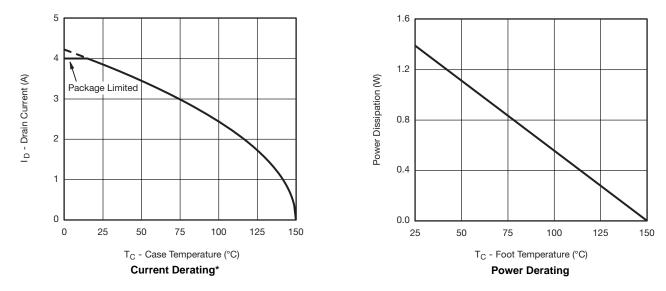


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

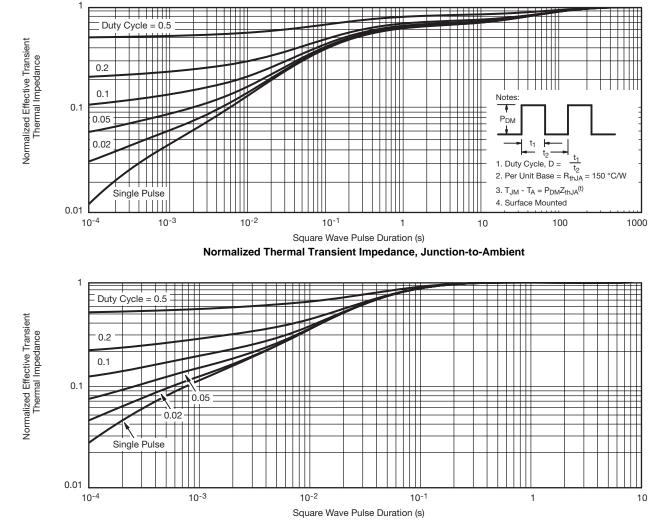




TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

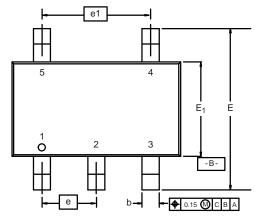
Normalized Thermal Transient Impedance, Junction-to-Foot

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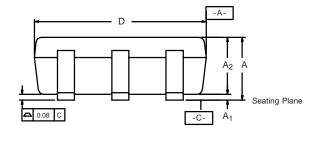
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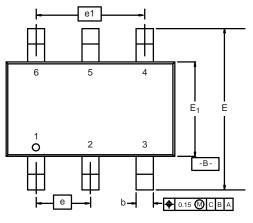


TSOP: 5/6–LEAD JEDEC Part Number: MO-193C

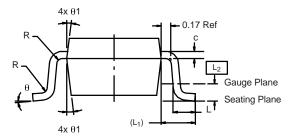








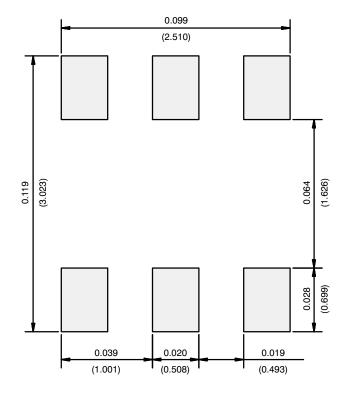
6-LEAD TSOP



	MILLIMETERS			INCHES			
Dim	Min	Nom	Max	Min	Nom	Max	
Α	0.91	-	1.10	0.036	-	0.043	
A ₁	0.01	-	0.10	0.0004	-	0.004	
A ₂	0.90	-	1.00	0.035	0.038	0.039	
b	0.30	0.32	0.45	0.012	0.013	0.018	
С	0.10	0.15	0.20	0.004	0.006	0.008	
D	2.95	3.05	3.10	0.116	0.120	0.122	
Е	2.70	2.85	2.98	0.106	0.112	0.117	
E ₁	1.55	1.65	1.70	0.061	0.065	0.067	
е		0.95 BSC		0.0374 BSC			
e ₁	1.80	1.90	2.00	0.071	0.075	0.079	
L	0.32	-	0.50	0.012	-	0.020	
L ₁		0.60 Ref		0.024 Ref			
L ₂	0.25 BSC			0.010 BSC			
R	0.10	-	-	0.004	-	-	
θ	0°	4°	8°	0°	4°	8°	
θ_1	7° Nom			7° Nom			
ECN: C-06593-Rev. I, 18-Dec-06 DWG: 5540							



RECOMMENDED MINIMUM PADS FOR TSOP-6



Recommended Minimum Pads Dimensions in Inches/(mm)



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